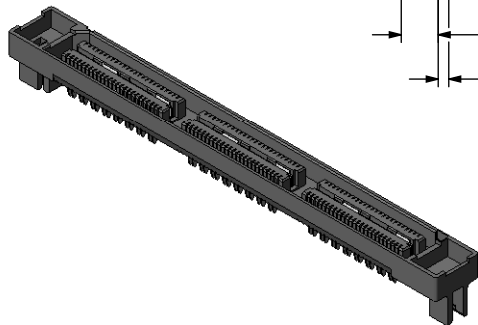
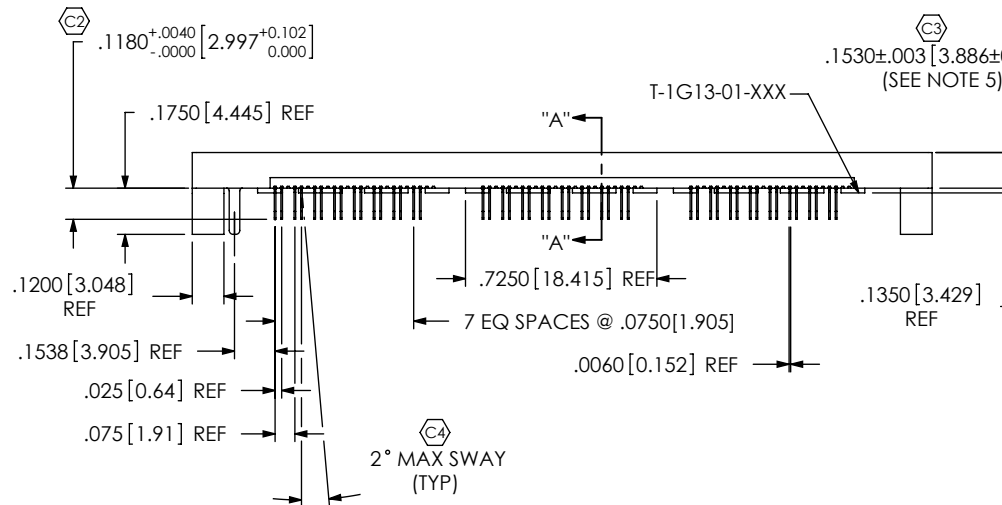
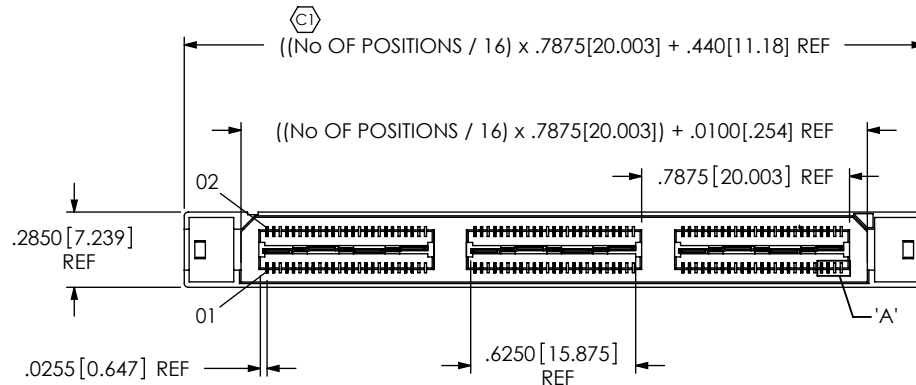


DO NOT
SCALE FROM
THIS PRINT



No OF POSITIONS

-016, -032, -048,
*-064, *-080
(PER ROW)

*SEE NOTE 11

LEAD STYLE

-01: .1530[3.886]

PLATING SPECIFICATION

-F: FLASH SELECTIVE GOLD

WITH MATTE TIN TAIL (SEE NOTE 6)

(USE C-162-XX-F & T-1G13-01-F)

-L: LIGHT SELECTIVE GOLD WITH MATTE TIN TAIL

(USE C-162-XX-L & T-1G13-01-L)

-H: HEAVY GOLD (USE C-162-XX-H & T-1G13-01-G)

-FTL: FLASH SELECTIVE GOLD, TIN/LEAD TAIL

(USE C-162-XX-FTL & T-1G13-01-FTL)

-STL: SELECTIVE GOLD, TIN/LEAD TAIL (USE C-162-XX-STL & T-1G13-01-STL)

*-064, -080 DO NOT DESIGN IN. SAMTEC WILL ONLY SUPPORT EXISTING BUSINESS 12/07/07.

EDGE MOUNT THICKNESS

-EM2: .064[1.63] +/- .004 PCB

(USE C-162-01-XXX & QSS-25-01-D-EM2-XX)

-EM3: (USE C-162-02-XXX

& QSS-25-01-D-EM3-XX)

SEE NOTE 10

-DP: DIFFERENTIAL PAIRS

ROW SPECIFICATION

-D: DOUBLE

(USE QSS-25-01-D-EMX-XX)

No OF BANKS

SECTION "A-A"

-EM2: .064[1.63] +/- .004 PCB

SECTION "A-A"

-EM3:

SEE NOTE 10

(DIFFERENT AS SHOWN, OTHERWISE SAME AS -EM2 PCB THICKNESS)

NOTES:

1. C REPRESENTS A CRITICAL DIMENSION.
2. CONTACT RETENTION: 6 OZ MIN.
3. GROUND PLANE RETENTION: 8 OZ MIN.
4. PARTS ARE MOLD TO POSITION.
5. MAX VARIANCE OF .002[.05].
6. -L PLATING CAN BE SUBSTITUTED FOR -F PLATING (CONTACT).
7. NOTE DELETED.
8. BOARD THICKNESS TO BE MEASURED FROM SOLDER PAD TO SOLDER PAD.
9. SEE www.samtec.com/processing/edgemt_tectalk/index.htm FOR INFORMATION ON PROCESSING EDGE MOUNT PARTS TO BOARDS.
10. -EM3 IS NOT A STANDARD OFFERING; AVAILABLE AS AN ASP ONLY. PLEASE CONTACT SAMTEC INTERCONNECT PROCESSING GROUP WITH ORDER INQUIRIES
11. FOR NEW APPLICATIONS REQUIRING THESE POSITIONS, PLEASE CONTACT SAMTEC INTERCONNECT PROCESSING GROUP.

UNLESS OTHERWISE SPECIFIED,
DIMENSIONS ARE IN INCHES.

TOLERANCES ARE:

DECIMALS ANGLES
.XX: ±.01 [.3] 2°
.XXX: ±.005 [.13]
.XXXX: ±.0020 [.051]

PROPRIETARY NOTE

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CONSENT OF SAMTEC, INC.

MATERIAL: DO NOT SCALE DRAWING

INSULATOR: LCP, COLOR: BLACK
CONTACT: PHOS BRONZE
GROUND PLANE: PHOS BRONZE

SHEET SCALE: 1.375:1

DESCRIPTION:

.635mm HS DIFF PAIR EDGE MOUNT SOCKET ASSEMBLY

DWG. NO.

QSS-XXX-01-XXX-D-DP-EMX

BY: KEVIN B

10/01/01

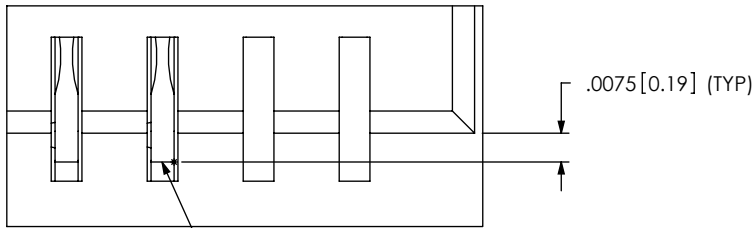
SHEET 1 OF 2

TABLE 2


No OF PAIRS	MAX BOW	GND PLANE COPLANARITY
-016, -032, -048	.004 [.10]	.004 [.10]
-064, -080	.006 [.15]	.006 [.15]



520 PARK EAST BLVD, NEW ALBANY, IN 47150
PHONE: 812-944-6733 FAX: 812-948-5047
e-Mail: info@SAMTEC.com code: 55322



DETAIL 'A'
SCALE 20: 1

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		DESCRIPTION: .635mm HS DIFF PAIR EDGE MOUNT SOCKET ASSEMBLY	
		DWG. NO. QSS-XXX-01-XXX-D-DP-EMX	
BY: KEVIN B		10/01/01	SHEET 2 OF 2